SMTJACK RECEPTACLE

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R223.424.000

Series : **MMBX**

PACKAGING

Standard	Unit	Other
100	**'W' option**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance	**50**	Ω
Frequency	**0-12.4**	GHz
VSWR	**1.065** + **0,0000**	x F(GHz) Maxi
Insertion loss	**0.12**	√F(GHz) dB Maxi
RF leakage	- (**100**	- F(GHz)) dB Maxi
Voltage rating	**330**	Veff Maxi
Dielectric withstanding voltage	**1000**	Veff mini
Insulation resistance	**1000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**10**	N mini
Axial force – Opposite end	**10**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Weight	**0,3050**	g

SPECIFICATION

ENVIRONMENTAL

Operating temperature	**-55/+155**	° C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

OTHER CHARACTERISTICS

Assembly instruction **NA**

Others :
to 6 GHz
Interface MMBX only,up to 2.5 GHz
PCB to PCB -45dB up to 2.5 GHz

Mated pair height 6.7mm

Issue : 0736 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

RADIALL®

SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste ‘SnAg4Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
   We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.

   A video camera is recommended for positioning of the component.

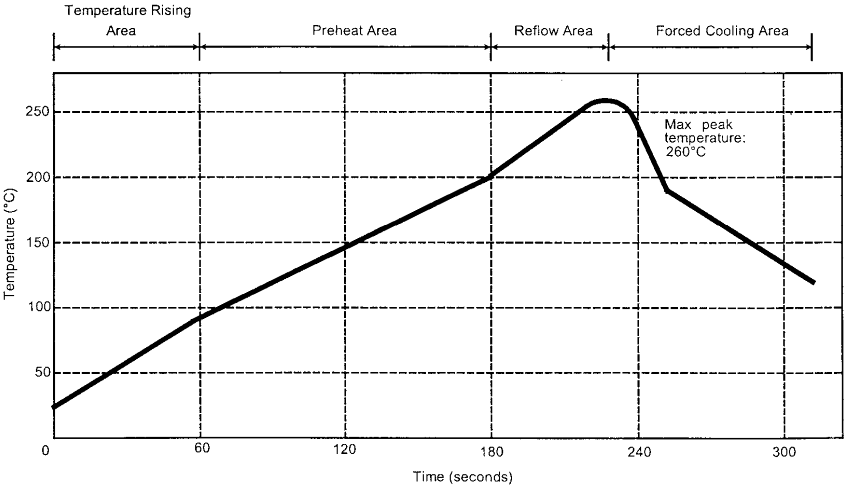
   Adhesive agents must not be used on the receptacle.

3. This process of soldering has been tested with convection oven.
   Below please find, the typical profile to use.

4. The cleaning of printed circuit boards is not obliged.

5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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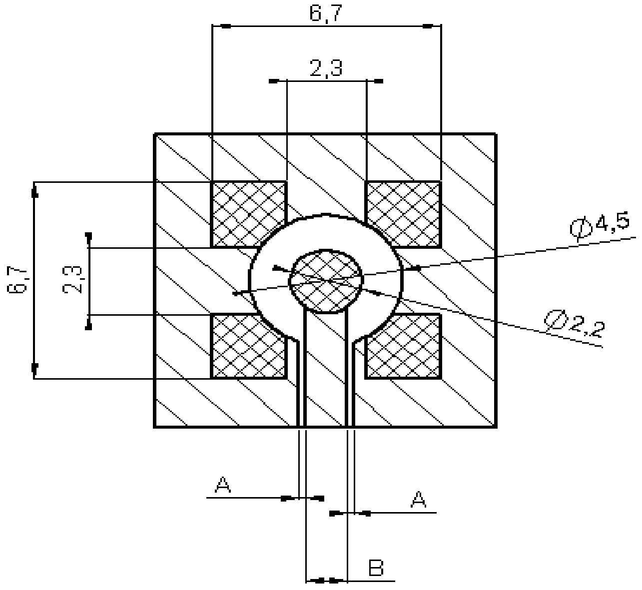
MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE
Pattern and signal are on the same side
The material of PCB is epoxy resin (FR4).
(Er = 4.6)
The solder resist should be printed
Except for the land pattern on the PCB

▨ Pattern

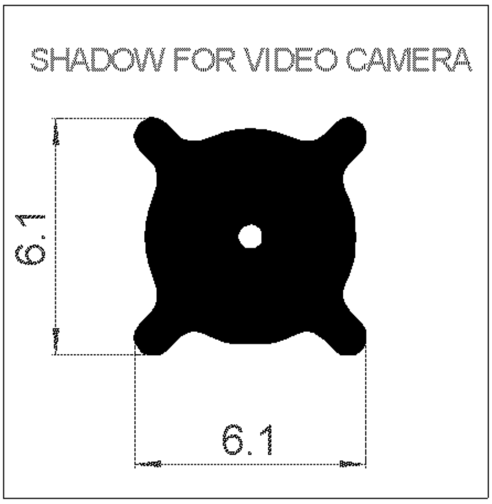
▩ Land for solder paste

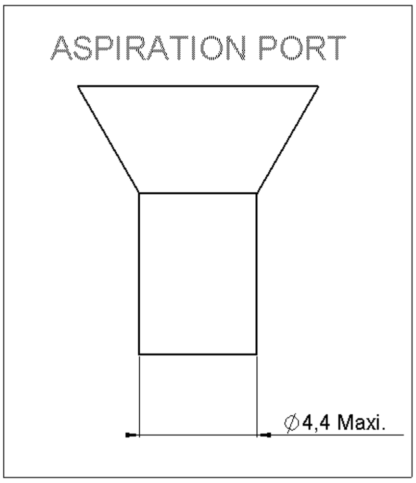
APPLICATION 75Ω
WITH B = 0,55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

APPLICATION 50Ω
WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210





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